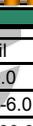


*** Valued Customer: If this stackup is accepted, please add this PDF to the production data package. ***

Job number: a3184	Material: MEGTRON-5775, F	External Stackup Report Report v1.74	 STREAMLINE CIRCUITS TIME AND TECHNOLOGY EXPERTS
Part number: ACD32RF4XXEVM, Rev: D	Impedance: Yes		
Customer: SVTRONICS, INC	Date: 20-Oct-2015		
Panel size: 18X24	Created by: Cesar Navarro		

Layer	Type	CU Weight	CU %	Material Description	Via Structure	Segment	Glass Style	Material Family	Dielectric constant @ 1GHz	Thickness After lamination [mil]
Soldermask										
1	Mixed	H	71	7.8 mil H/H		Core	2-3313	MEGTRON-5775	3.71	1.60
2	Plane	H	86	Press thk = 3.91 mil		Prepreg	3313(56)	R-1650V	4.20	3.91
3	Plane	H	82	12.0 mil H/H		Core	2-1506	R-1755V	4.50	12.00
4	Mixed	H	76	Press thk = 3.87 mil		Prepreg	3313(56)	R-1650V	4.20	3.87
5	Plane	H	86	12.0 mil H/H		Core	2-1506	R-1755V	4.50	12.00
6	Mixed	H	82	Press thk = 3.91 mil		Prepreg	3313(56)	R-1650V	4.20	3.91
7	Plane	H	86	8.0 mil H/H		Core	2-2116	R-1755V	4.40	8.00
8	Mixed	H	75							1.60
Soldermask										

Specification (Over mask on plated copper):	mil
Overall Board Thickness:	60.0
Tolerance:	+6.0/-6.0
Min-Max Board Thickness:	54.0-66.0

Anticipated Board Thickness:	mil
After lamination:	55.89
Over mask on plated copper:	59.89

Grain in 18" Dimension

Impedance Table

InSolver

Layer	Impedance Requirement [ohms]	Tolerance [ohms]		Type	Upper Reference	Lower Ref	Designed Line Width [Mil]	Designed Spacing [Mil]	Finished Line Width [Mil]	Finished Spacing [Mil]	Impedance Simulation [ohms]
		+	-								
1	100	10	10	Differential		2	9	6.00	8.4	6.60	100.197
1	50	5	5	Single Ended		2	19		15		49.398
8	100	10	10	Differential		7	8	6.00	7.4	6.60	99.520
8	50	5	5	Single Ended		7	19		13.5		49.440

Remarks

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- * Any targeted thickness .0046" and greater shall have a minimum tolerance of +/- .001 after lamination.
- * Any targeted thickness .0045" and below shall not be held to the minimum dielectric .0035429" as specified in IPC-6012 section 3.6.2.15. Unless agreed upon in writing from Streamline Circuits Inc. The minimum thickness per this exception shall not be less than .0009839" per IPC-6012 section 3.6.2.15.
- * Streamline is not responsible for any build that does not meet IPC-6012 Bow & Twist requirements due to unbalanced dielectrics, unbalanced copper percentages or copper weights.